

Switch-mode Power Rectifiers

DPAK Surface Mount Package

MBRD320G, MBRD330G, MBRD340G, MBRD350G, MBRD360G

These state-of-the-art devices are designed for use as output rectifiers, free wheeling, protection and steering diodes in switching power supplies, inverters and other inductive switching circuits.

Features

- Extremely Fast Switching
- Extremely Low Forward Drop
- Platinum Barrier with Avalanche Guardrings
- NRVBD and SBRD Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes; 260°C Max. for 10 Seconds
- ESD Ratings:
 - ◆ Machine Model = C
 - ◆ Human Body Model = 3B

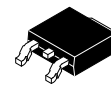


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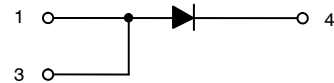
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SCHOTTKY BARRIER RECTIFIERS

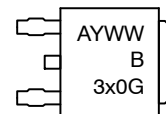
3.0 AMPERES, 20 – 60 VOLTS



DPAK
CASE 369C



MARKING DIAGRAM



| | |
|------|----------------------|
| A | = Assembly Location* |
| Y | = Year |
| WW | = Work Week |
| B3x0 | = Device Code |
| x | = 2, 3, 4, 5, or 6 |
| G | = Pb-Free Package |

* The Assembly Location Code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejector pin), the front side assembly code may be blank.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

MBRD320G, MBRD330G, MBRD340G, MBRD350G, MBRD360G

MAXIMUM RATINGS

| Rating | Symbol | MBRD/SBRD8 | | | | | Unit |
|--|---------------------------------|-------------|-----|-----|-----|-----|------------------|
| | | 320 | 330 | 340 | 350 | 360 | |
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 20 | 30 | 40 | 50 | 60 | V |
| Average Rectified Forward Current ($T_C = +125^\circ\text{C}$) | $I_{F(AV)}$ | 3 | | | | | A |
| Peak Repetitive Forward Current, $T_C = +125^\circ\text{C}$ (Square Wave, Duty = 0.5) | I_{FRM} | 6 | | | | | A |
| Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz) | I_{FSM} | 75 | | | | | A |
| Peak Repetitive Reverse Surge Current (2 μs , 1 kHz) | I_{RRM} | 1 | | | | | A |
| Operating Junction Temperature Range (Note 1) | T_J | -65 to +175 | | | | | $^\circ\text{C}$ |
| Storage Temperature Range | T_{stg} | -65 to +175 | | | | | $^\circ\text{C}$ |
| Voltage Rate of Change (Rated V_R) | dv/dt | 10,000 | | | | | V/ μs |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|--|-----------------|-------|--------------------|
| Maximum Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 6 | $^\circ\text{C/W}$ |
| Maximum Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 80 | $^\circ\text{C/W}$ |

2. Rating applies when surface mounted on the minimum pad size recommended.

ELECTRICAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|--|--------|-----------------------------|------|
| Maximum Instantaneous Forward Voltage (Note 3) $i_F = 3$ Amps, $T_C = +25^\circ\text{C}$ $i_F = 3$ Amps, $T_C = +125^\circ\text{C}$ $i_F = 6$ Amps, $T_C = +25^\circ\text{C}$ $i_F = 6$ Amps, $T_C = +125^\circ\text{C}$ | V_F | 0.6 0.45 0.7 0.625 | V |
| Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_C = +25^\circ\text{C}$) (Rated dc Voltage, $T_C = +125^\circ\text{C}$) | i_R | 0.2 20 | mA |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

MBRD320G, MBRD330G, MBRD340G, MBRD350G, MBRD360G

ORDERING INFORMATION

| Device | Package | Shipping† |
|-------------------|-------------------|-------------------|
| MBRD320G | DPAK (Pb-Free) | 75 Units / Rail |
| SBRD8320G* | | 75 Units / Rail |
| SBRD8320G-VF01* | | 75 Units / Rail |
| MBRD320RLG | | 1,800 Tape & Reel |
| MBRD320T4G | | 2,500 Tape & Reel |
| SBRD8320T4G* | | 2,500 Tape & Reel |
| SBRD8320T4G-VF01* | | 2,500 Tape & Reel |
| MBRD330G | | 75 Units / Rail |
| SBRD8330G* | | 75 Units / Rail |
| SBRD8330G-VF01* | | 75 Units / Rail |
| MBRD330RLG | | 1,800 Tape & Reel |
| MBRD330T4G | | 2,500 Tape & Reel |
| SBRD8330T4G* | | 2,500 Tape & Reel |
| SBRD8330T4G-VF01* | | 2,500 Tape & Reel |
| MBRD340G | | 75 Units / Rail |
| SBRD8340G* | | 75 Units / Rail |
| SBRD8340G-VF01* | | 75 Units / Rail |
| MBRD340RLG | | 1,800 Tape & Reel |
| MBRD340T4G | | 2,500 Tape & Reel |
| SBRD8340T4G* | | 2,500 Tape & Reel |
| SBRD8340T4G-VF01* | | 2,500 Tape & Reel |
| MBRD350G | | 75 Units / Rail |
| SBRD8350G* | | 75 Units / Rail |
| SBRD8350G-VF01* | | 75 Units / Rail |
| MBRD350RLG | | 1,800 Tape & Reel |
| SBRD8350RLG* | | 1,800 Tape & Reel |
| SBRD8350RLG-VF01* | | 1,800 Tape & Reel |
| MBRD350T4G | | 2,500 Tape & Reel |
| SBRD8350T4G* | | 2,500 Tape & Reel |
| SBRD8350T4G-VF01* | | 2,500 Tape & Reel |
| MBRD360G | | 75 Units / Rail |
| SBRD8360G* | | 75 Units / Rail |
| SBRD8360G-VF01* | | 75 Units / Rail |
| MBRD360RLG | | 1,800 Tape & Reel |
| SBRD8360RLG* | | 1,800 Tape & Reel |
| SBRD8360RLG-VF01* | | 1,800 Tape & Reel |
| MBRD360T4G | | 2,500 Tape & Reel |
| NRVBD360VT4G* | | 2,500 Tape & Reel |
| SBRD8360T4G* | | 2,500 Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NRVBD and SBRD Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

TYPICAL CHARACTERISTICS

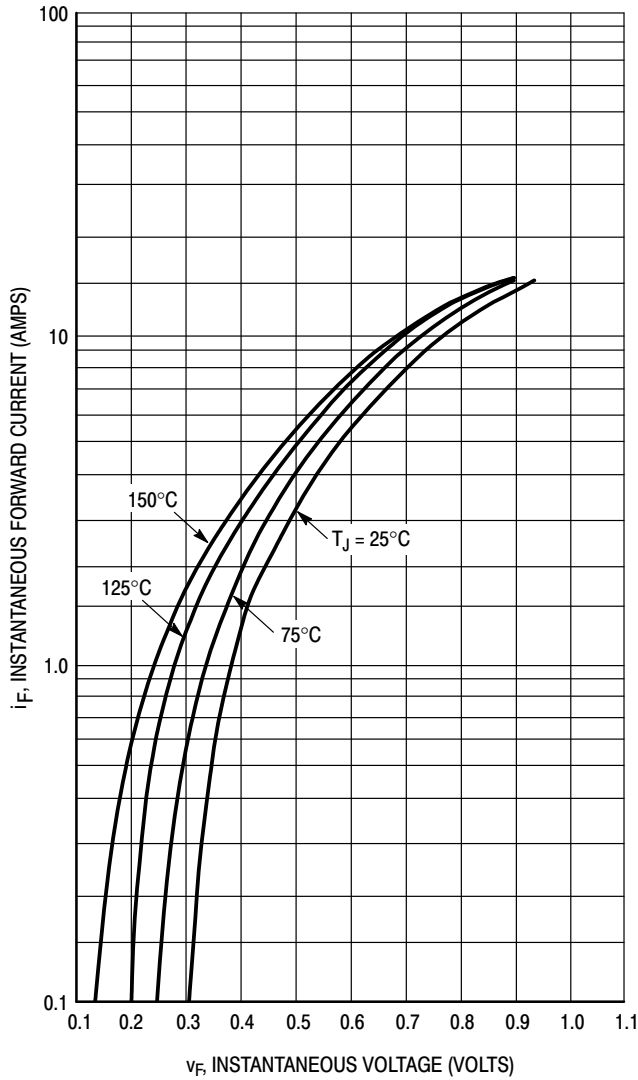
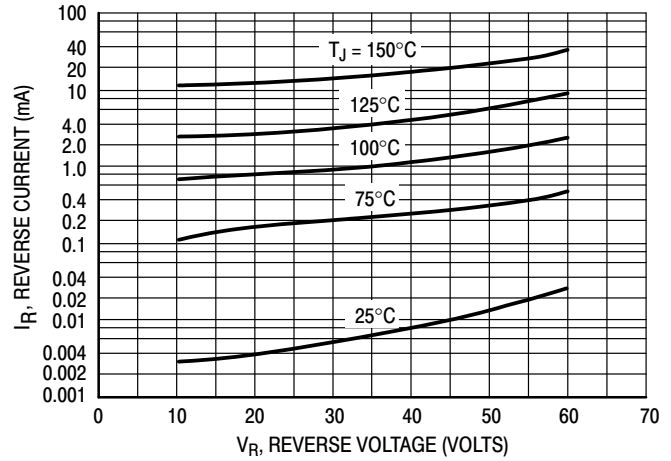


Figure 1. Typical Forward Voltage



*The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these curves if V_R is sufficient below rated V_R .

Figure 2. Typical Reverse Current

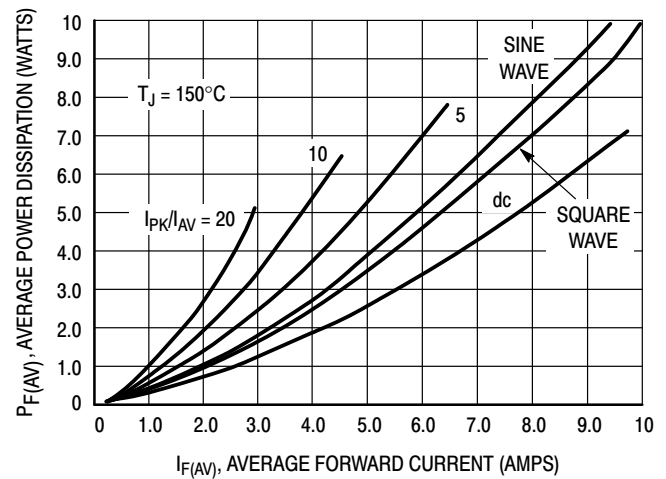


Figure 3. Average Power Dissipation

TYPICAL CHARACTERISTICS

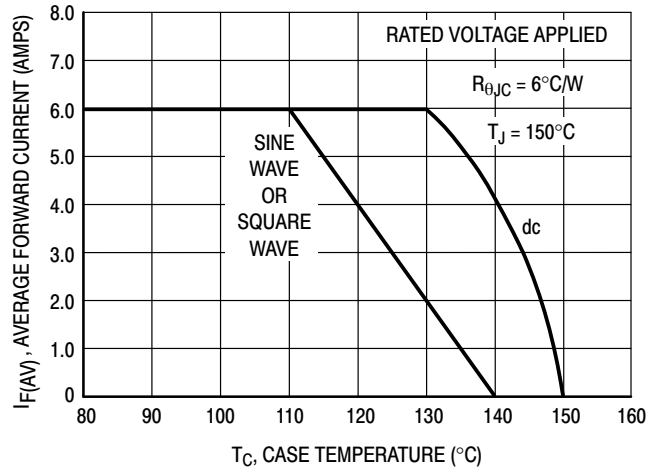


Figure 4. Current Derating, Case

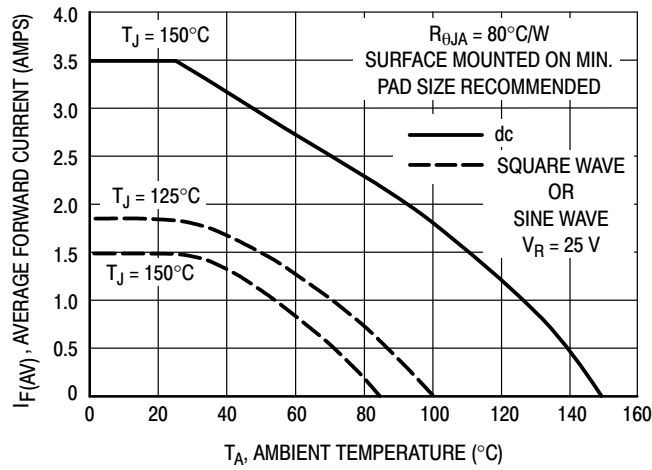


Figure 5. Current Derating, Ambient

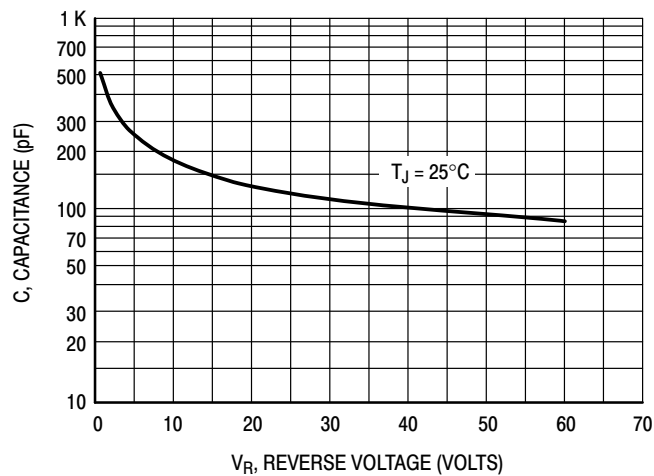
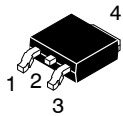


Figure 6. Typical Capacitance

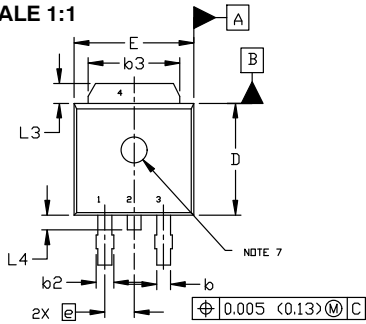
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



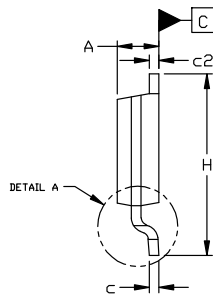
DPAK (SINGLE GAUGE) CASE 369C ISSUE G

DATE 31 MAY 2023

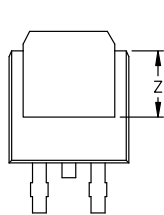
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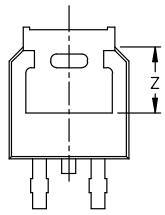
TOP VIEW



SIDE VIEW

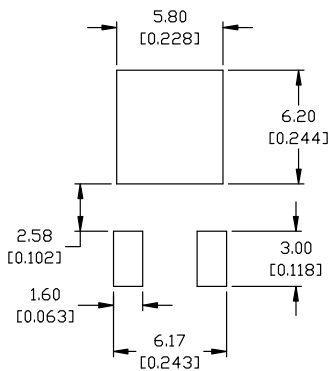


BOTTOM VIEW



BOTTOM VIEW

ALTERNATE CONSTRUCTIONS



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

STYLE 1:

- PIN 1. BASE
- 2. COLLECTOR
- 3. EMITTER
- 4. COLLECTOR

STYLE 2:

- PIN 1. GATE
- 2. DRAIN
- 3. SOURCE
- 4. DRAIN

STYLE 3:

- PIN 1. ANODE
- 2. CATHODE
- 3. ANODE
- 4. CATHODE

STYLE 4:

- PIN 1. CATHODE
- 2. ANODE
- 3. GATE
- 4. ANODE

STYLE 5:

- PIN 1. GATE
- 2. ANODE
- 3. CATHODE
- 4. ANODE

STYLE 6:

- PIN 1. MT1
- 2. MT2
- 3. GATE
- 4. MT2

STYLE 7:

- PIN 1. GATE
- 2. COLLECTOR
- 3. EMITTER
- 4. COLLECTOR

STYLE 8:

- PIN 1. N/C
- 2. CATHODE
- 3. ANODE
- 4. CATHODE

STYLE 9:

- PIN 1. ANODE
- 2. CATHODE
- 3. RESISTOR ADJUST
- 4. CATHODE

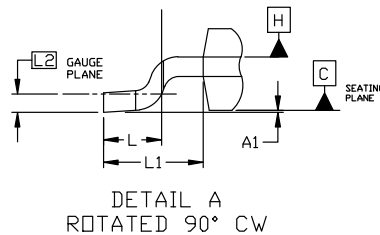
STYLE 10:

- PIN 1. CATHODE
- 2. ANODE
- 3. CATHODE
- 4. ANODE

NOTES:

1. DIMENSIONING AND TOLERANCING ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 0.086 | 0.094 | 2.18 | 2.38 |
| A1 | 0.000 | 0.005 | 0.00 | 0.13 |
| b | 0.025 | 0.035 | 0.63 | 0.89 |
| b2 | 0.028 | 0.045 | 0.72 | 1.14 |
| b3 | 0.180 | 0.215 | 4.57 | 5.46 |
| c | 0.018 | 0.024 | 0.46 | 0.61 |
| c2 | 0.018 | 0.024 | 0.46 | 0.61 |
| D | 0.235 | 0.245 | 5.97 | 6.22 |
| E | 0.250 | 0.265 | 6.35 | 6.73 |
| e | 0.090 | BSC | 2.29 | BSC |
| H | 0.370 | 0.410 | 9.40 | 10.41 |
| L | 0.055 | 0.070 | 1.40 | 1.78 |
| L1 | 0.114 | REF | 2.90 | REF |
| L2 | 0.020 | BSC | 0.51 | BSC |
| L3 | 0.035 | 0.050 | 0.89 | 1.27 |
| L4 | ---- | 0.040 | --- | 1.01 |
| Z | 0.155 | ---- | 3.93 | --- |

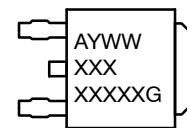


DETAIL A
ROTATED 90° CW

GENERIC MARKING DIAGRAM*



IC



Discrete

- XXXXXX = Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

| | | |
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